

In the Claims:

93 28. The apparatus of claim 19, wherein the layer of underfill adhesive formed on the active surface of the flip chip integrated circuit has a height less than the height of the solder bumps.

In the Drawings:

The Applicants request that the attached Figures 5(a) and 5(b) be added to the application. These figures were inadvertently not included when the application was filed. A review of Figures 5(a) and 5(b) indicates that all of the elements except dam 140 are previously described and illustrated in the specification as filed. The dam 140, however, is fully described in paragraph [0029] of the specification. Therefore, the figures do not add any new matter.

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